DIP WETTING TESTER(SWB-2)

Feature

- The entire procedure, from Flux application (w/ Flux Temperature Control Function) to Measurement End is automated. Reducing unstable measurement results, and user error.
- Complies with the Wetting test method according to JIS Z3198 (Lead Free Solder Test Method) standards.
- Easily change Solder and Flux when necessary.
- Electro-Balance Sensor detects a small force.
- Efficiently analyze data with the exclusive PC software. (option)
- An optional cover allows for wetting evaluation in a N2 environment. (option)
- Micro Wetting Balance Measuring method is available.(option)

Product specification

Item		**Specification**
Model Name		SWB-2
Load sensor	**Principle**	Electro-Balance Sensor (EBS)

	Measuring Range	30mN - -30mN
	Accuracy	±0.05mN
	Resolution	0.01mN
Temp. Sensor	**Measuring Range**	0 - 450C
	Accuracy	±3℃
Insertion Time		1 - 200s
Insertion Depth		0.01 - 20.00mm (0.01mm step)
Insertion Speed		0.1～30mm/s
Solder Temp. Setting		Room Temp. - 400C (Micro-wetting : Room Temp. - 320C)
Japanese Standard		Automatic Measurement (Flux Application, Removal and Measurement) JIS Z3198-4 and C60068-2-54 ,C60068-2-54, C6008-2-69 JEITA ET7411(Solder Bath)
International Standard		ISO 9455-16 IEC 60068-2-54 and 60068-2-69 (Solder bath) ANSI J-STD-003, MIL STD-883 (Method 2022.2) and IPC TM-650 (2.4.14.2)
N_2 Measurement		Oxygen Concentration: 500ppm max. (optional)
Power Supply		AC100,115,220,240V (To be specified when ordering) Approx 400W
Outer Dimension		300(W)×330(D)×370(H)（mm）
Weight		Approx. 16kg

* The measurement accuracy of the load sensor excludes the error margin such as the vibrations or others.

* When high-speed infiltrating, the vibration of the table might influence the measurement result.

* The above specifications are subject to change without notice.